Claims

- [c1] An apparatus comprising:
 - a holder adapted to hold and rotate a substrate;
 - a shield surrounding said substrate; and
 - a dispenser positioned to dispense a fluid on said substrate.
 - wherein a surface of said shield facing said substrate comprises a semi-permeable material.
- [02] The apparatus in claim 1, wherein said semi-permeable material prevents fluid ejected from the surface of the rotating substrate from forming into a mist and being re-deposited back on said substrate.
- [c3] The apparatus in claim 2, wherein said mist comprises said fluid and foreign material particles.
- [04] The apparatus in claim 1, wherein said semi-permeable material comprises one of an absorptive material, a screen material, a perforated material and a finned material.
- [05] The apparatus in claim 1, wherein said semi-permeable material comprises a disposable material and is adapted to be periodically removed from said shield and re-

- placed.
- [06] The apparatus in claim 1, wherein said semi-permeable material comprises a permanent part of said shield.
- [c7] The apparatus in claim 1, wherein fluid ejected from the surface of the rotating substrate is collected by and drains down said semi-permeable material.
- [08] A cleaning apparatus used during the production of semiconductor wafers, said apparatus comprising:
 - a holder adapted to hold and rotate a semiconductor wafer;
 - a shield surrounding said semiconductor wafer; and a dispenser positioned to dispense a cleaning fluid on said semiconductor wafer,
 - wherein a surface of said shield facing said semiconductor wafer comprises a semi-permeable material.
- [09] The apparatus in claim 8, wherein said semi-permeable material prevents cleaning fluid ejected from the surface of the rotating semiconductor wafer from forming into a mist and being re-deposited back on said semiconductor wafer.
- [c10] The apparatus in claim 9, wherein said mist comprises said cleaning fluid and foreign material particles.

- [c11] The apparatus in claim 8, wherein said semi-permeable material comprises one of an absorptive material, a screen material, a perforated material and a finned material.
- [c12] The apparatus in claim 8, wherein said semi-permeable material comprises a disposable material and is adapted to be periodically removed from said shield and replaced.
- [c13] The apparatus in claim 8, wherein said semi-permeable material comprises a permanent part of said shield.
- [c14] The apparatus in claim 8, wherein cleaning fluid ejected from the surface of the rotating semiconductor wafer is collected by and drains down said semi-permeable material.
- [c15] A method for cleaning a surface of a semiconductor wafer, said method comprising:
 - positioning a shield around said semiconductor wafer, wherein a surface of said shield facing said semiconductor wafer comprises a semi-permeable material;
 - rotating said semiconductor wafer within said shield; and
 - applying a cleaning fluid on a surface of the sub-

strate.

- [c16] The method in claim 15, wherein said semi-permeable material prevents cleaning fluid ejected from the surface of the rotating semiconductor wafer from forming into a mist and being redeposited back on said semiconductor wafer.
- [c17] The method in claim 16, wherein said mist comprises said cleaning fluid and foreign material particles.
- [c18] The method in claim 15, wherein said semi-permeable material comprises one of an absorptive material, a screen material, a perforated material and a finned material.
- [c19] The method in claim 15, wherein cleaning fluid ejected from the surface of the rotating semiconductor wafer is collected by and drains down said semi-permeable material.
- [c20] The method in claim 15, further comprising removing and replacing said semi-permeable material.